



Electronics for the Future

On adding additional manufacturing sites for power diodes
(PMDU(M), PMDTM, PMDE)
currently limited to the ROHM Assembly Manufacturing Co., Ltd.
(Application No.:4026006)

1.September.2026

ROHM Co., Ltd.

General Purpose Device Business Headquarters

General Purpose Devices Business Division

AP Engineering Department 4G

Official NameName	Used in This Document
ROHM Assembly Manufacturing Co., Ltd.	Japan (Okayama) Plant
ROHM Electronics (Malaysia) Sdn. Bhd.	Malaysia Plant
ROHM Semiconductor (China) Co., Ltd.	China (Tianjin) Plant

※Note: From the following page onward,
The facilities will be referred to by one of the names listed above.

Contents

We kindly request the additional approval of the PMDU(M) (SOD-123FL) package and the PMDTM (SOD-128) package for production at the Malaysia plant and the China (Tianjin) plant. In addition, we kindly request the additional approval of the PMDE (DO-219AD) package for production at the Malaysia plant.

Purpose

To strengthen Business Continuity Management (BCM) and meet increasing market demand, ROHM has established additional production capability for the PMDU(M) (SOD-123FL) package and the PMDTM (SOD-128) package at the Malaysia plant and China (Tianjin) plant. To ensure a stable supply of products to our customers, we kindly request your approval for the addition of these two manufacturing sites. In addition, we kindly request your approval for the addition of the Malaysia plant as a manufacturing site for the PMDE (DO-219AD) package.

Target product

This change applies to diode products manufactured by ROHM in the PMDU(M) (SOD-123FL) package, PMDTM (SOD-128) package, and PMDE (DO-219AD) package. Please refer to the attached document for detailed product information.

Change details

Package	PMDU(M) 〈SOD-123FL〉 、 PMDTM 〈SOD-128〉	PMDE 〈 DO-219AD 〉
Item	Manufacturing Site	
Before Change	Japan (Okayama)	Japan (Okayama)
After Change	Japan (Okayama), Malaysia, China (Tianjin)	Japan (Okayama), Malaysia

Model name change

There is no change to the product part number.

5M Change Point (PMDU(M) (SOD-123FL))

5M change point

		Target	Manufacture plant			Change point
			Current	New		
			Japan	Malaysia	China	
Change point of 5M	人 (Man)	Man	Japan staff Out sourcing staff	Malaysia staff Out sourcing staff	China staff Out sourcing staff	Yes
			HR License			No
	設備 (Machine)	Production	Matrix flame			No
		Terminal treatment	Out sourcing	In house+Out sourcing	Out sourcing	Yes
	材料 (Material)	Wafer	Si			No
		Flame	Cu flame			No
		Paste	Sn-Ag-Pb			No
		Resin	Halogen free			No
		Plating	Sn100%			No
		Currier tape	Antistatic products			No
		Cover tape	Antistatic products			No
	方法 (Method)	Production	Matrix flame			No
		Terminal treatment	Out sourcing	In house+Out sourcing	Out sourcing	Yes
	測定 (Measurement)	Inspection	In house tester			No

5M Change Point (PMDTM <SOD-128>)

5M change point

		Target	Manufacture plant			Change point
			Current	New		
			Japan	Malaysia	China	
Change point of 5M	人 (Man)	Man	Japan staff Out sourcing staff	Malaysia staff Out sourcing staff	China staff Out sourcing staff	Yes
			HR License			No
	設備 (Machine)	Production	Matrix flame			No
		Terminal treatment	Out sourcing	In house+Out sourcing	In house+Out sourcing	Yes
	材料 (Material)	Wafer	Si			No
		Flame	Cu flame			No
		Paste	Sn-Ag-Pb			No
		Resin	Halogen free			No
		Plating	Sn100%			No
		Currier tape	Antistatic products			No
		Cover tape	Antistatic products			No
		方法 (Method)	Production	Matrix flame		
	Terminal treatment		Out sourcing	In house+Out sourcing	In house+Out sourcing	Yes
	測定	Inspection	In house tester			No

5M change point

		Target	Manufacture plant		Change point
			Current		
			Japan	Malaysia	
Change point of 5M	人 (Man)	Man	Japan staff Out sourcing staff	Malaysia staff Out sourcing staff	Yes
			HR License		No
	設備 (Machine)	Production	Matrix flame		No
		Terminal treatment	Out sourcing	In house+Out sourcing	Yes
	材料 (Material)	Wafer	Si		No
		Flame	Cu flame		No
		Paste	Sn-Ag-Pb		No
		Resin	Halogen free		No
		Plating	Sn100%		No
		Currier tape	Antistatic products		No
		Cover tape	Antistatic products		No
	方法 (Method)	Production	Matrix flame		No
		Terminal treatment	Out sourcing	In house+Out sourcing	Yes
	測定 (Measurement)	Inspection	In house tester		No

Schedule

	2026				2027											
	9	10	11	12	1	2	3	4	5	6	7	8	9	10	11	12
Change application	◆															
Sample submission																
Approval Due Date												◆				
Start mass production																

5MChange Point and Schedule (PMDU(M) 〈SOD-123FL〉 PMDTM 〈SOD-128〉)

5M Change point

Item	PMDU(M) 〈SOD-123FL〉 / PMDTM 〈SOD-128〉			Change point
Manufacturing Site	ROHM Assembly Manufacturing Co., Ltd.	ROHM Electronics (Malaysia) Sdn. Bhd.	ROHM Semiconductor (China) Co.,Ltd.	YES
Country of Origin	Japan (Okayama)	Malaysia	China (Tianjin)	YES
Man:人	Qualified operators at each manufacturing site (certified under ROHM's internal operator qualification system)			YES
Material:材料	Common wafer source			No
	Common materials			No
Machine:設備	Existing equipment			No
Method:方法	Wire-frame process			No
Measurement:測定	Common test program			No

Schedule

	2026				2027											
	9	10	11	12	1	2	3	4	5	6	7	8	9	10	11	12
Change application	◆															
Sample submission																
Approval Due Date												◆				
Start mass production																

5MChange Point and Schedule (PMDE (DO-219AD))

5M Change point

Item	PMDE (DO-219AD)		Change point
Manufacturing Site	ROHM Assembly Manufacturing Co., Ltd.	ROHM Electronics (Malaysia) Sdn. Bhd.	YES
Country of Origin	Japan (Okayama)	Malaysia	YES
Man:人	Qualified operators at each manufacturing site (certified under ROHM's internal operator qualification system)		YES
Material:材料	Common wafer source		No
	Common materials		No
Machine:設備	Existing equipment		No
Method:方法	Wire-frame process		No
Measurement:測定	Common test program		No

Schedule

	2026				2027											
	9	10	11	12	1	2	3	4	5	6	7	8	9	10	11	12
Change application	◆															
Sample submission																
Approval Due Date												◆				
Start mass production																

Differences (PMDU(M) 〈SOD-123FL〉)

Item	PMDU(M) 〈SOD-123FL〉		
Manufacturing Site	ROHM Assembly Manufacturing Co., Ltd.	ROHM Electronics (Malaysia) Sdn. Bhd.	ROHM Semiconductor (China) Co.,Ltd.
Country of Origin	Japan (Okayama)	Malaysia	China (Tianjin)
Package Dimensions	No Change		
Reference Land Pattern	No Change		
Terminal Finish	No Change (100% Sn Plating)		
Marking Method	No Change Laser marking (scan method), 30-dot specification		
Internal Structure	No Change Semiconductor chip embedded type		
Molding Resin	No Change Halogen-free		
Internal Elements	No Change		
Absolute Maximum Ratings	No Change		
Electrical Characteristics	No Change		

There is no difference in product specifications.

Differences (PMDTM<SOD-128>)



Item	PMDTM <SOD-128>		
Manufacturing Site	ROHM Assembly Manufacturing Co., Ltd.	ROHM Electronics (Malaysia) Sdn. Bhd.	ROHM Semiconductor (China) Co.,Ltd.
Country of Origin	Japan (Okayama)	Malaysia	China (Tianjin)
Package Dimensions	No Change		
Reference Land Pattern	No Change		
Terminal Finish	No Change (100% Sn Plating)		
Marking Method	No Change Laser marking (scan method), 30-dot specification		
Internal Structure	No Change Semiconductor chip embedded type		
Molding Resin	No Change Halogen-free		
Internal Elements	No Change		
Absolute Maximum Ratings	No Change		
Electrical Characteristics	No Change		

There is no difference in product specifications.

Differences (PMDE < DO-219AD >)



Item	PMDE < DO-219AD >	
Manufacturing Site	ROHM Assembly Manufacturing Co., Ltd.	ROHM Electronics (Malaysia) Sdn. Bhd.
Country of Origin	Japan (Okayama)	Malaysia
Package Dimensions	No Change	
Reference Land Pattern	No Change	
Terminal Finish	No Change (100% Sn Plating)	
Marking Method	No Change Laser marking (scan method), 30-dot specification	
Internal Structure	No Change Semiconductor chip embedded type	
Molding Resin	No Change Halogen-free	
Internal Elements	No Change	
Absolute Maximum Ratings	No Change	
Electrical Characteristics	No Change	

There is no difference in product specifications.

Package verification reliability test results (PMDU(M) <SOD-123FL>)



Test model : PMDU(M) <SOD-123FL>

- ※ As pretreatment conditions, baking (oven 125°C for 24 hours)
- ⇒ leaving at high temperature and high humidity (85°C for 85%168 hours)
- ⇒ Reflow (peak 250°C x 3 times) was carried out.

Although three lots were evaluated for each condition, only the data from one representative lot is presented in this report.

ROHM Electronics (Malaysia) Sdn. Bhd.

[Pn/n]

ROHM Semiconductor (China) Co.,Ltd.

[Pn/n]

Test item		Test conditions	Test time and result			
HTRB	High temperature Bias	Ta=150°C、VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
THB	High temperature and high humidity bias	Ta=85°C、Rh=85%、VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
PCT	Steam pressurization	Ta=121°C、Rh=100%、2atm	100h	300h	500h	
			0/77	0/77	0/77	
TCY	Temperature Cycle	- 55°C(30min)~ +150°C(30min)	100cyc	300cyc	500cyc	1000cyc
			0/77	0/77	0/77	0/77

Test item		Test conditions	Test time and result			
HTRB	High temperature Bias	Ta=150°C、VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
THB	High temperature and high humidity bias	Ta=85°C、Rh=85%、VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
PCT	Steam pressurization	Ta=121°C、Rh=100%、2atm	100h	300h	500h	
			0/77	0/77	0/77	
TCY	Temperature Cycle	- 55°C(30min)~ +150°C(30min)	100cyc	300cyc	500cyc	1000cyc
			0/77	0/77	0/77	0/77

Package verification reliability test results (PMDTM<SOD-128>)



Test model : PMDTM<SOD-128>

- ※ As pretreatment conditions, baking (oven 125°C for 24 hours)
- ⇒ leaving at high temperature and high humidity (85°C for 85%168 hours)
- ⇒ Reflow (peak 250°C x 3 times) was carried out.

Although three lots were evaluated for each condition, only the data from one representative lot is presented in this report.

ROHM Electronics (Malaysia) Sdn. Bhd.

[Pn/n]

ROHM Semiconductor (China) Co.,Ltd.

[Pn/n]

Test item		Test conditions	Test time and result			
HTRB	High temperature Bias	Ta=150°C、VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
THB	High temperature and high humidity bias	Ta=85°C、Rh=85%、VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
PCT	Steam pressurization	Ta=121°C、Rh=100%、2atm	100h	300h	500h	
			0/77	0/77	0/77	
TCY	Temperature Cycle	- 55°C(30min)~ +150°C(30min)	100cyc	300cyc	500cyc	1000cyc
			0/77	0/77	0/77	0/77

Test item		Test conditions	Test time and result			
HTRB	High temperature Bias	Ta=150°C、VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
THB	High temperature and high humidity bias	Ta=85°C、Rh=85%、VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
PCT	Steam pressurization	Ta=121°C、Rh=100%、2atm	100h	300h	500h	
			0/77	0/77	0/77	
TCY	Temperature Cycle	- 55°C(30min)~ +150°C(30min)	100cyc	300cyc	500cyc	1000cyc
			0/77	0/77	0/77	0/77

Test model : PMDE < DO-219AD >

- ※ As pretreatment conditions, baking (oven 125°C for 24 hours)
- ⇒ leaving at high temperature and high humidity (85°C for 85%168 hours)
- ⇒ Reflow (peak 250°C x 3 times) was carried out.

Although three lots were evaluated for each condition, only the data from one representative lot is presented in this report.

ROHM Electronics (Malaysia) Sdn. Bhd.

[Pn/n]

Test item		Test conditions	Test time and result			
HTRB	High temperature Bias	Ta=150°C、 VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
THB	High temperature and high humidity bias	Ta=85°C、Rh=85%、 VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
PCT	Steam pressurization	Ta=121°C、 Rh=100%、 2atm	100h	300h	500h	
			0/77	0/77	0/77	
TCY	Temperature Cycle	- 55°C(30min)~ +150°C(30min)	100cyc	300cyc	500cyc	1000cyc
			0/77	0/77	0/77	0/77



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